

# PEMB19; PUMB19

PNP/PNP resistor-equipped transistors;  
R1 = 22 k $\Omega$ , R2 = open

Rev. 02 — 1 September 2009

Product data sheet

## 1. Product profile

### 1.1 General description

PNP/PNP resistor-equipped transistors

Table 1. Product overview

| Type number | Package |       | NPN/PNP complement | NPN/PNP complement |
|-------------|---------|-------|--------------------|--------------------|
|             | NXP     | JEITA |                    |                    |
| PEMB19      | SOT666  | -     | PEMD19             | PEMH19             |
| PUMB19      | SOT363  | SC-88 | PUMD19             | PUMH19             |

### 1.2 Features

- Built-in bias resistors
- Simplifies circuit design
- Reduces component count
- Reduces pick and place cost

### 1.3 Applications

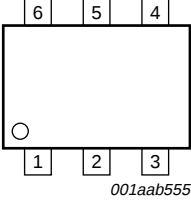
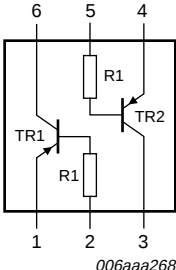
- Low current peripheral driver
- Control of IC inputs
- Replacement of general-purpose transistors in digital applications

### 1.4 Quick reference data

Table 2. Quick reference data

| Symbol           | Parameter                 | Conditions | Min  | Typ | Max  | Unit       |
|------------------|---------------------------|------------|------|-----|------|------------|
| V <sub>CEO</sub> | collector-emitter voltage | open base  | -    | -   | -50  | V          |
| I <sub>O</sub>   | output current (DC)       |            | -    | -   | -100 | mA         |
| R1               | bias resistor 1 (input)   |            | 15.4 | 22  | 28.6 | k $\Omega$ |

2. Pinning information

| Table 3. Pinning |                        |                                                                                                  |                                                                                                  |
|------------------|------------------------|--------------------------------------------------------------------------------------------------|--------------------------------------------------------------------------------------------------|
| Pin              | Description            | Simplified outline                                                                               | Symbol                                                                                           |
| 1                | GND (emitter) TR1      | <br>001aab555 | <br>006aaa268 |
| 2                | input (base) TR1       |                                                                                                  |                                                                                                  |
| 3                | output (collector) TR2 |                                                                                                  |                                                                                                  |
| 4                | GND (emitter) TR2      |                                                                                                  |                                                                                                  |
| 5                | input (base) TR2       |                                                                                                  |                                                                                                  |
| 6                | output (collector) TR1 |                                                                                                  |                                                                                                  |

3. Ordering information

| Table 4. Ordering information |         |                                          |         |
|-------------------------------|---------|------------------------------------------|---------|
| Type number                   | Package |                                          |         |
|                               | Name    | Description                              | Version |
| PEMB19                        | -       | plastic surface mounted package; 6 leads | SOT666  |
| PUMB19                        | SC-88   | plastic surface mounted package; 6 leads | SOT363  |

4. Marking

| Table 5. Marking codes |                             |
|------------------------|-----------------------------|
| Type number            | Marking code <sup>[1]</sup> |
| PEMB19                 | 6D                          |
| PUMB19                 | T3*                         |

[1] \* = -: made in Hong Kong  
\* = p: made in Hong Kong  
\* = t: made in Malaysia  
\* = W: made in China

## 5. Limiting values

**Table 6. Limiting values**

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

| Symbol                | Parameter                 | Conditions               | Min       | Max  | Unit |
|-----------------------|---------------------------|--------------------------|-----------|------|------|
| <b>Per transistor</b> |                           |                          |           |      |      |
| V <sub>CBO</sub>      | collector-base voltage    | open emitter             | -         | -50  | V    |
| V <sub>CEO</sub>      | collector-emitter voltage | open base                | -         | -50  | V    |
| V <sub>EBO</sub>      | emitter-base voltage      | open collector           | -         | -5   | V    |
| I <sub>O</sub>        | output current (DC)       |                          | -         | -100 | mA   |
| I <sub>CM</sub>       | peak collector current    |                          | -         | -100 | mA   |
| P <sub>tot</sub>      | total power dissipation   | T <sub>amb</sub> ≤ 25 °C |           |      |      |
|                       | SOT363                    |                          | [1] -     | 200  | mW   |
|                       | SOT666                    |                          | [1] [2] - | 200  | mW   |
| T <sub>stg</sub>      | storage temperature       |                          | -65       | +150 | °C   |
| T <sub>j</sub>        | junction temperature      |                          | -         | 150  | °C   |
| T <sub>amb</sub>      | ambient temperature       |                          | -65       | +150 | °C   |
| <b>Per device</b>     |                           |                          |           |      |      |
| P <sub>tot</sub>      | total power dissipation   | T <sub>amb</sub> ≤ 25 °C |           |      |      |
|                       | SOT363                    |                          | [1] -     | 300  | mW   |
|                       | SOT666                    |                          | [1] [2] - | 300  | mW   |

[1] Device mounted on a FR4 printed-circuit board, single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.

## 6. Thermal characteristics

**Table 7. Thermal characteristics**

| Symbol                | Parameter                                   | Conditions               | Min       | Typ | Max | Unit |
|-----------------------|---------------------------------------------|--------------------------|-----------|-----|-----|------|
| <b>Per transistor</b> |                                             |                          |           |     |     |      |
| R <sub>th(j-a)</sub>  | thermal resistance from junction to ambient | T <sub>amb</sub> ≤ 25 °C |           |     |     |      |
|                       | SOT363                                      |                          | [1] -     | -   | 625 | K/W  |
|                       | SOT666                                      |                          | [1] [2] - | -   | 625 | K/W  |
| <b>Per device</b>     |                                             |                          |           |     |     |      |
| R <sub>th(j-a)</sub>  | thermal resistance from junction to ambient | T <sub>amb</sub> ≤ 25 °C |           |     |     |      |
|                       | SOT363                                      |                          | [1] -     | -   | 416 | K/W  |
|                       | SOT666                                      |                          | [1] [2] - | -   | 416 | K/W  |

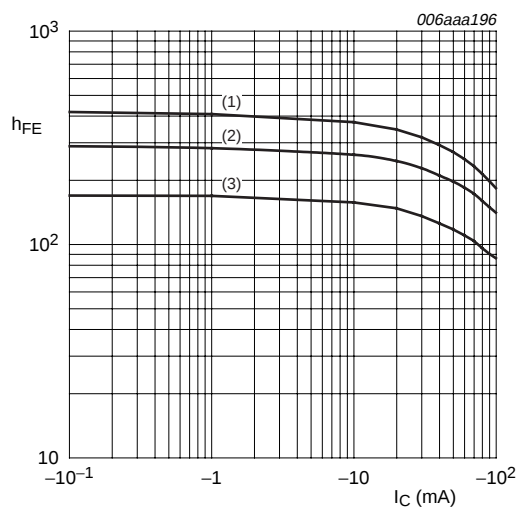
[1] Device mounted on a FR4 printed-circuit board, single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.

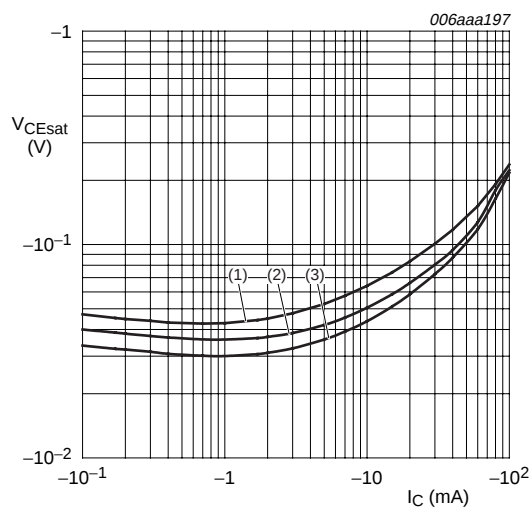
## 7. Characteristics

**Table 8. Characteristics**
 $T_{amb} = 25\text{ °C}$  unless otherwise specified

| Symbol                | Parameter                            | Conditions                                                              | Min  | Typ | Max  | Unit |
|-----------------------|--------------------------------------|-------------------------------------------------------------------------|------|-----|------|------|
| <b>Per transistor</b> |                                      |                                                                         |      |     |      |      |
| $I_{CBO}$             | collector-base cut-off current       | $V_{CB} = -50\text{ V}$ ; $I_E = 0\text{ A}$                            | -    | -   | -100 | nA   |
| $I_{CEO}$             | collector-emitter cut-off current    | $V_{CE} = -30\text{ V}$ ; $I_B = 0\text{ A}$                            | -    | -   | -1   | μA   |
|                       |                                      | $V_{CE} = -30\text{ V}$ ; $I_B = 0\text{ A}$ ; $T_j = 150\text{ °C}$    | -    | -   | -50  | μA   |
| $I_{EBO}$             | emitter-base cut-off current         | $V_{EB} = -5\text{ V}$ ; $I_C = 0\text{ A}$                             | -    | -   | -100 | nA   |
| $h_{FE}$              | DC current gain                      | $V_{CE} = -5\text{ V}$ ; $I_C = -1\text{ mA}$                           | 100  | -   | -    |      |
| $V_{CEsat}$           | collector-emitter saturation voltage | $I_C = -10\text{ mA}$ ; $I_B = -0.5\text{ mA}$                          | -    | -   | -150 | mV   |
| R1                    | bias resistor 1 (input)              |                                                                         | 15.4 | 22  | 28.6 | kΩ   |
| $C_c$                 | collector capacitance                | $V_{CB} = -10\text{ V}$ ; $I_E = i_e = 0\text{ A}$ ; $f = 1\text{ MHz}$ | -    | -   | 3    | pF   |



- $V_{CE} = -5\text{ V}$
- (1)  $T_{amb} = 100\text{ °C}$
  - (2)  $T_{amb} = 25\text{ °C}$
  - (3)  $T_{amb} = -40\text{ °C}$

**Fig 1. DC current gain as a function of collector current; typical values**


- $I_C/I_B = 20$
- (1)  $T_{amb} = 100\text{ °C}$
  - (2)  $T_{amb} = 25\text{ °C}$
  - (3)  $T_{amb} = -40\text{ °C}$

**Fig 2. Collector-emitter saturation voltage as a function of collector current; typical values**

8. Package outline

Plastic surface-mounted package; 6 leadsSOT363

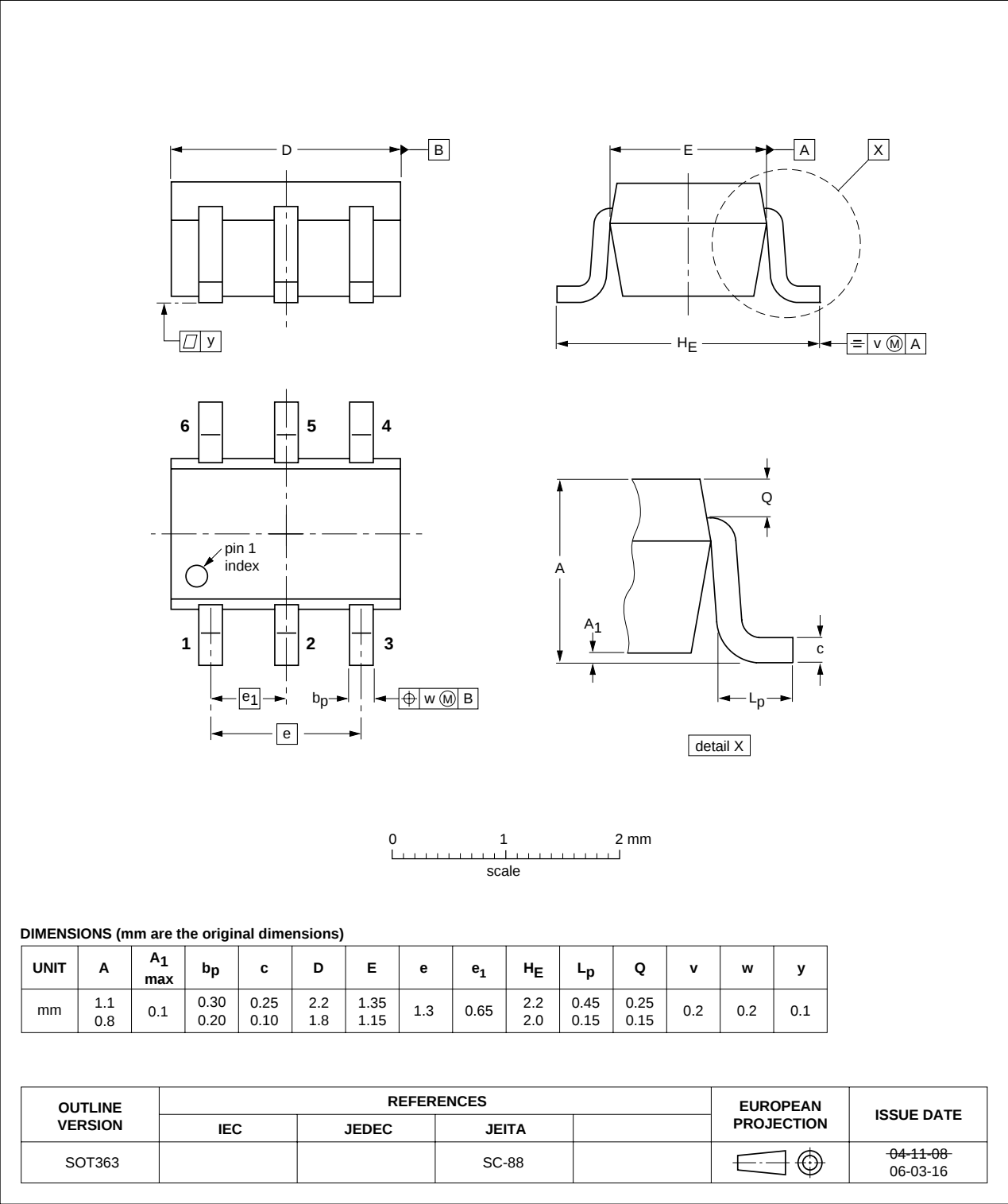


Fig 3. Package outline SOT363 (SC-88)

Plastic surface-mounted package; 6 leads

SOT666

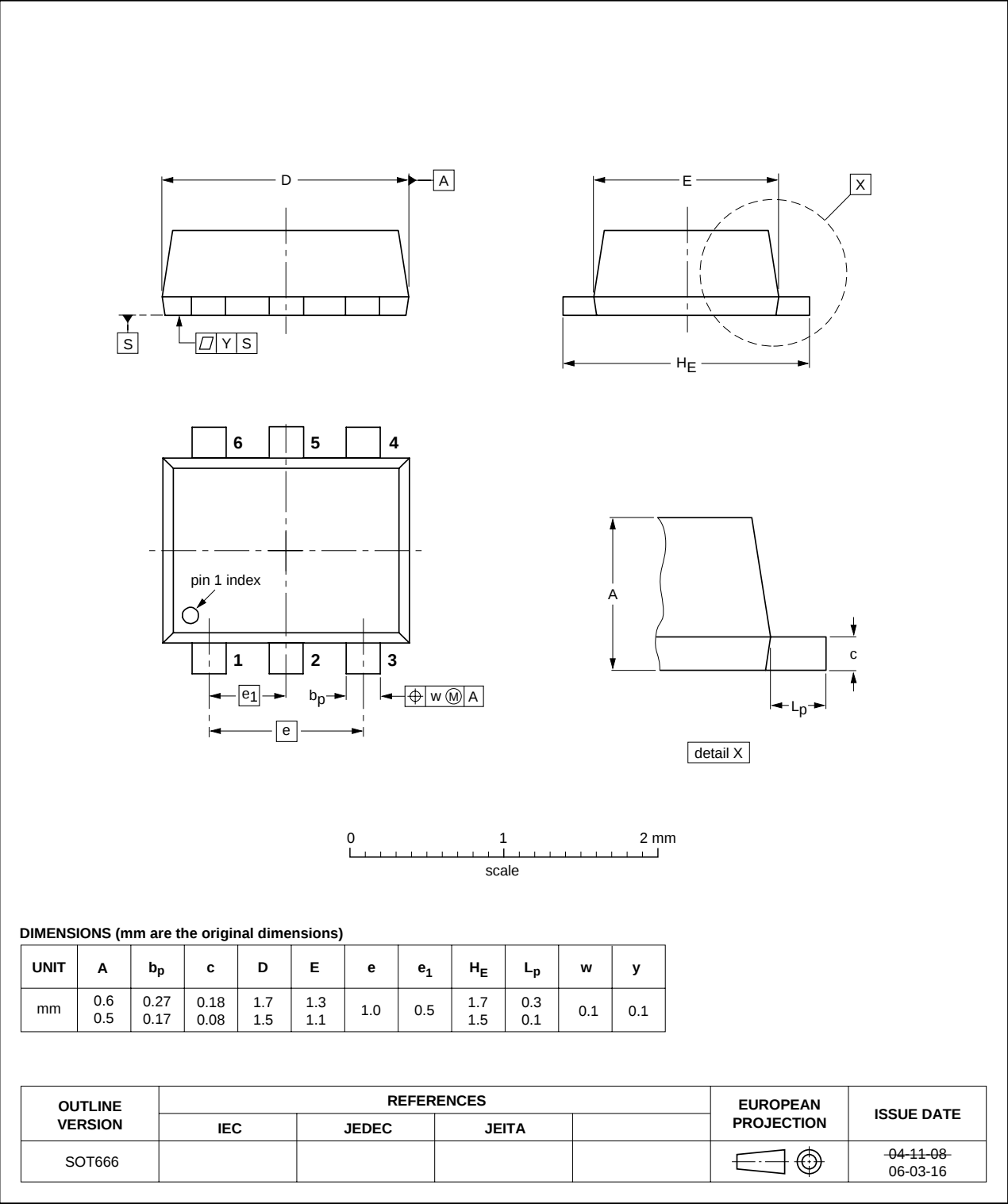


Fig 4. Package outline SOT666

## 9. Packing information

**Table 9. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code. [\[1\]](#)

| Type number | Package | Description                                            | Packing quantity |      |       |
|-------------|---------|--------------------------------------------------------|------------------|------|-------|
|             |         |                                                        | 3000             | 4000 | 10000 |
| PEMB19      | SOT666  | 4 mm pitch, 8 mm tape and reel;                        | -                | -115 | -     |
| PUMB19      | SOT363  | 4 mm pitch, 8 mm tape and reel; T1 <a href="#">[2]</a> | -115             | -    | -135  |
| PUMB19      | SOT363  | 4 mm pitch, 8 mm tape and reel; T2 <a href="#">[3]</a> | -125             | -    | -165  |

[1] For further information and the availability of packing methods, see [Section 12](#).

[2] T1: normal taping

[3] T2: reverse taping

## 10. Revision history

**Table 10.** Revision history

| Document ID     | Release date                                                                                                                                                                                                                                                                                                                                                                        | Data sheet status  | Change notice | Supersedes      |
|-----------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------------|---------------|-----------------|
| PEMB19_PUMB19_2 | 20090901                                                                                                                                                                                                                                                                                                                                                                            | Product data sheet | -             | PEMB19_PUMB19_1 |
| Modifications:  | <ul style="list-style-type: none"><li>• This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content.</li><li>• <a href="#">Figure 3 "Package outline SOT363 (SC-88)"</a>: updated</li><li>• <a href="#">Figure 4 "Package outline SOT666"</a>: updated</li></ul> |                    |               |                 |
| PEMB19_PUMB19_1 | 20050202                                                                                                                                                                                                                                                                                                                                                                            | Product data sheet | -             | -               |

## 11. Legal information

### 11.1 Data sheet status

| Document status <sup>[1][2]</sup> | Product status <sup>[3]</sup> | Definition                                                                            |
|-----------------------------------|-------------------------------|---------------------------------------------------------------------------------------|
| Objective [short] data sheet      | Development                   | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet    | Qualification                 | This document contains data from the preliminary specification.                       |
| Product [short] data sheet        | Production                    | This document contains the product specification.                                     |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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